	Material Comp © Copyright 2005. Il international and Par	osition Dec PC, Bannockb American co	c laration ourn, Illinois. A opyright conver	All rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the succession of the s	ubstances s all lower	within the r level mate	manufacture erials for wh	er listed it hich the m	em. Note: i anufacturer	f the item is an as r has engineering	ssembly with lowe responsibility.	
1752-21.1					Form Type Distribute						eous Materia	rials and Mfg Information				
Supplier	r Information															
Company name*				Company unique ID			Unique ID Authority					Response Date*				
onsemi											2024-05-20					
Contact N	lame	Title - Contact]	Phone - Contact*					Email - Contact*					
Product-H	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*						
Product-H	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	te Version Manufacturing Site		ing Site	V	Weight*	UOM	Unit Type		
	MUR810G			REC T0220 8A 100V ULTFST			2024-05-20 CN5			1962.01		mg	Each			
Aanufa	cturing Proccess Information	tion														
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 M		J-STD-020 MSI	L Rating	Peak Process Body Temperate		emperatur	ure Max Time at Peak Temper		Temperat	ure Numb	per of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C		С	30 se		second	ds 3				
omments	6															
or more i	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	А	Lead (Pb)	7439-92-1	7a	74.682	mg
			Supplier	Tin (Sn)	7440-31-5		8.298	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9	mg		Metal Hydroxide	proprietary data		38.073	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.925	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		81.585	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		13.5975	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted)